502180687 01/02/2013

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Milind S. Bhagavat	12/20/2012
Sampath Komarapalayam Velayudham Karikalan	12/21/2012
Rezaur Rahman Khan	12/20/2012

RECEIVING PARTY DATA

Name:	Broadcom Corporation
Street Address:	5300 California Avenue
City:	Irvine
State/Country:	CALIFORNIA
Postal Code:	92617-3038

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13725699

CORRESPONDENCE DATA

Fax Number: 6123328352

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 425-502-8860

Email: chartness@cpaglobal.com

Correspondent Name: Jeffrey S. Weaver

Address Line 1: c/o CPA Global, P.O. Box 52050
Address Line 4: Minneapolis, MINNESOTA 55402

ATTORNEY DOCKET NUMBER:	A05.01840001

NAME OF SUBMITTER: Jeffrey S. Weaver

Total Attachments: 6

source=A05.01840001 Executed Assignment#page1.tif source=A05.01840001 Executed Assignment#page2.tif source=A05.01840001 Executed Assignment#page3.tif source=A05.01840001 Executed Assignment#page4.tif source=A05.01840001 Executed Assignment#page5.tif source=A05.01840001 Executed Assignment#page6.tif

PATENT REEL: 029552 FRAME: 0807 OF \$40.00 13/25688

ASSIGNMENT

In consideration of the sum of one dollar (\$1.00) or equivalent and other good and valuable consideration paid to the undersigned inventors: Milind S. Bhagavat, Sampath Komarapalayam Velayudham Karikalan and Rezaur Rahman Khan hereby sells and assigns to Broadcom Corporation, a corporation formed under the laws of California, whose mailing address is 5300 California Avenue, Irvine, California 92617-3038 (hereafter referred to as the Assignee), his/her entire right, title and interest, including the right to sue for past infringement and to collect for all past, present, and future damages, for the United States of America (as defined in 35 U.S.C. § 100) and throughout the world,

- (a) in the invention(s) known as <u>INTEGRATION OF CHIPS AND SILICON-BASED TRENCH CAPACITORS USING LOW PARASITIC SILICON-LEVEL CONNECTIONS</u> for which application(s) for patent in the United States of America has a filing date or a 371(c) date of <u>December 21, 2012</u>, (also known as United States Application No. <u>13/725,699</u>) (Attorney Docket No. <u>A05.01840001</u>), in any and all applications thereon, in any and all Letters Patent(s) therefore, and
- (b) in any and all applications that claim the benefit of the patent application listed above in part (a), including non-provisional applications, continuing (continuation, divisional, or continuation-in-part) applications, reissues, extensions, renewals and reexaminations of the patent application or Letters Patent therefore listed above in part (a), to the full extent of the term or terms for which Letters Patent issue, and
- (c) in any and all inventions described in the patent application listed above in part (a), and in any and all forms of intellectual property protection derivable from such patent application, and that are derivable from any and all continuing patent applications, reissues, extensions, renewals and reexaminations of such patent application, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefore; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignee, its successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignor had this assignment and sale not been made.

The undersigned inventors agree to execute all papers necessary in connection with the application(s) and any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s)

thereof and also to execute separate assignments in connection with such application(s) as the Assignee may deem necessary or expedient.

The undersigned inventors agree to execute all papers necessary in connection with any interference or patent enforcement action (judicial or otherwise) related to the application(s) or any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application(s) thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference or patent enforcement action.

The undersigned inventors hereby represent that he/she has full right to convey the entire interest herein assigned, and that he/she has not executed, and will not execute, any agreement in conflict therewith.

The undersigned inventors hereby grant the patent practitioners associated with CUSTOMER NUMBER 68365 the power to insert in this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

IN WITNESS WHEREOF, executed by the undersigned inventors on the date opposite his/her name.

Date: 12/20/2012	Signature of Inventor:	
	Milind S. Bhagavat	
Date:	Signature of Inventor:	
and the second	Sampath Komarapalayam Velayudham Karikala	I
Date:	Signature of Inventor:	
	Rezaur Rahman Khan	

ASSIGNMENT

In consideration of the sum of one dollar (\$1.00) or equivalent and other good and valuable consideration paid to the undersigned inventors: Milind S. Bhagavat, Sampath Komarapalayam Velayudham Karikalan and Rezaur Rahman Khan hereby sells and assigns to Broadcom Corporation, a corporation formed under the laws of California, whose mailing address is 5300 California Avenue, Irvine, California 92617-3038 (hereafter referred to as the Assignee), his/her entire right, title and interest, including the right to sue for past infringement and to collect for all past, present, and future damages, for the United States of America (as defined in 35 U.S.C. § 100) and throughout the world,

- (a) in the invention(s) known as <u>INTEGRATION OF CHIPS AND SILICON-BASED TRENCH CAPACITORS USING LOW PARASITIC SILICON-LEVEL CONNECTIONS</u> for which application(s) for patent in the United States of America has a filing date or a 371(c) date of <u>December 21, 2012</u>, (also known as United States Application No. <u>13/725,699</u>) (Attorney Docket No. <u>A05.01840001</u>), in any and all applications thereon, in any and all Letters Patent(s) therefore, and
- (b) in any and all applications that claim the benefit of the patent application listed above in part (a), including non-provisional applications, continuing (continuation, divisional, or continuation-in-part) applications, reissues, extensions, renewals and reexaminations of the patent application or Letters Patent therefore listed above in part (a), to the full extent of the term or terms for which Letters Patent issue, and
- (c) in any and all inventions described in the patent application listed above in part (a), and in any and all forms of intellectual property protection derivable from such patent application, and that are derivable from any and all continuing patent applications, reissues, extensions, renewals and reexaminations of such patent application, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefore; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignee, its successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignor had this assignment and sale not been made.

The undersigned inventors agree to execute all papers necessary in connection with the application(s) and any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s)

thereof and also to execute separate assignments in connection with such application(s) as the Assignee may deem necessary or expedient.

The undersigned inventors agree to execute all papers necessary in connection with any interference or patent enforcement action (judicial or otherwise) related to the application(s) or any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application(s) thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference or patent enforcement action.

The undersigned inventors hereby represent that he/she has full right to convey the entire interest herein assigned, and that he/she has not executed, and will not execute, any agreement in conflict therewith.

The undersigned inventors hereby grant the patent practitioners associated with CUSTOMER NUMBER 68365 the power to insert in this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

IN WITNESS WHEREOF, executed by the undersigned inventors on the date opposite his/her name.

Date:	Signature of Inventor:
Date: Dec 21, 2012	Milind S. Bhagavat Signature of Inventor: Sampath Komarapalayam Velayudham Karikalar
Date:	Signature of Inventor: Rezaur Rahman Khan

ASSIGNMENT

In consideration of the sum of one dollar (\$1.00) or equivalent and other good and valuable consideration paid to the undersigned inventors: Milind S. Bhagavat, Sampath Komarapalayam Velayudham Karikalan and Rezaur Rahman Khan hereby sells and assigns to Broadcom Corporation, a corporation formed under the laws of California, whose mailing address is 5300 California Avenue, Irvine, California 92617-3038 (hereafter referred to as the Assignee), his/her entire right, title and interest, including the right to sue for past infringement and to collect for all past, present, and future damages, for the United States of America (as defined in 35 U.S.C. § 100) and throughout the world,

- (a) in the invention(s) known as <u>INTEGRATION OF CHIPS AND SILICON-BASED TRENCH CAPACITORS USING LOW PARASITIC SILICON-LEVEL CONNECTIONS</u> for which application(s) for patent in the United States of America has a filing date or a 371(c) date of <u>December 21, 2012</u>, (also known as United States Application No. <u>13/725,699</u>) (Attorney Docket No. <u>A05.01840001</u>), in any and all applications thereon, in any and all Letters Patent(s) therefore, and
- (b) in any and all applications that claim the benefit of the patent application listed above in part (a), including non-provisional applications, continuing (continuation, divisional, or continuation-in-part) applications, reissues, extensions, renewals and reexaminations of the patent application or Letters Patent therefore listed above in part (a), to the full extent of the term or terms for which Letters Patent issue, and
- (c) in any and all inventions described in the patent application listed above in part (a), and in any and all forms of intellectual property protection derivable from such patent application, and that are derivable from any and all continuing patent applications, reissues, extensions, renewals and reexaminations of such patent application, including, without limitation, patents, applications, utility models, inventor's certificates, and designs together with the right to file applications therefore; and including the right to claim the same priority rights from any previously filed applications under the International Agreement for the Protection of Industrial Property, or any other international agreement, or the domestic laws of the country in which any such application is filed, as may be applicable;

all such rights, title and interest to be held and enjoyed by the above-named Assignee, its successors, legal representatives and assigns to the same extent as all such rights, title and interest would have been held and enjoyed by the Assignor had this assignment and sale not been made.

The undersigned inventors agree to execute all papers necessary in connection with the application(s) and any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s)

Page 1 of 2

Appl. No. <u>13/725,699</u> Docket No. A05.01840001/BU24599

thereof and also to execute separate assignments in connection with such application(s) as the Assignee may deem necessary or expedient.

The undersigned inventors agree to execute all papers necessary in connection with any interference or patent enforcement action (judicial or otherwise) related to the application(s) or any non-provisional, continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application(s) thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference or patent enforcement action.

The undersigned inventors hereby represent that he/she has full right to convey the entire interest herein assigned, and that he/she has not executed, and will not execute, any agreement in conflict therewith.

The undersigned inventors hereby grant the patent practitioners associated with CUSTOMER NUMBER 68365 the power to insert in this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

IN WITNESS WHEREOF, executed by the undersigned inventors on the date opposite his/her name.

Date:	Signature of Inventor:
	Milind S. Bhagavat
Date:	Signature of Inventor:
h /a ilm	Sampath Komarapalayam Velayudham Karikalan
Date: 12/20/12	Signature of Inventor:
1 1	Rezaur Rahman Khan